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IN THE SPECIFICATION

Please amend the specification as follows.

[0022] The conductive particles 210 inside the bonded anisotropic conductive film 208 have an electrically insulating outermost flux layer 216. According to one aspect of the present invention, Aside from the capacity to the flux layer 206, which is known in the conventional art to contain halide free and water soluble activators generally applied to the surfaces in the printed circuit board before soldering, is applied as an outermost layer of the conductive particles to function as a cleanser to cleanup impurities such as ions, grease and the like on from the surface contacts of both the silicon chip 200 and the carrier 204, so that the electrical properties of the surface contacts can be substantially improved. Further, the flux layer 206 also assists contribute to the binding of the bonded anisotropic conductive film to contact point surface and forms common metallic bonds. In addition, the flux layer 216 being an insulator can also prevents short-circuiting of the contact points 202 and 206 with conductive particles 210 outside the bonding regions. Consequently, smallest permissible pitch between neighboring contact points can be reduced. In other words, neighboring contact points can be closer together.